



ER4012

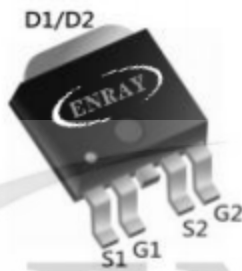
N-Ch and P-Ch Fast Switching MOSFET

Features

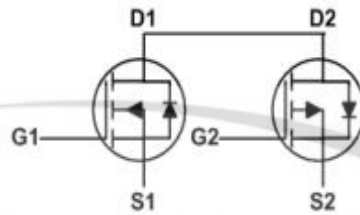
The ER4012 is the high performance complementary N-ch and P-ch MOSFETs with high cell density, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications. The meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Product Summary

BVDSS	RDS(on)	ID
40V	17mΩ	25A
-40V	35mΩ	-25A



TO-252-4L



Maximum Ratings(Ta=25°C unless otherwise noted)

Parameter	Symbol	Rating		Unit
		N-Ch	P-Ch	
Drain-Source Voltage	VDS	40	-40	V
Gate-Source Voltage	VGS	±20	±20	
Continuous Drain Current	ID@TC=25°C	25	-25	A
Continuous Drain Current	ID@TC=100°C	18	-16	
Pulsed Drain Current ²	IDM	46	-40	
Single Pulse Avalanche Energy ³	EAS	28	66	mJ
Avalanche Current	IAS	17.8	-27.2	A
Total Power Dissipation	PD@TC=25°C	25	31.3	W
Storage Temperature Range	TSTG	-55 to 150		°C
Operating Junction Temperature	TJ	-55 to 150		

Thermal Data

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction-Ambient ¹	RθJA	-	62	°C/W
Thermal Resistance Junction-Case	RθJC	-	5	°C/W

N-Channel Electrical Characteristics(T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static Parameters ③						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D = 250μA	40			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V			1	μA
Gate-Body leakage Current	I _{GSS}	V _{GS} =±20 V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =250uA	1.0	1.5	2.5	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =8A		17	22	mΩ
		V _{GS} =4.5V, I _D =5A		25	35	mΩ
Dynamic Parameters ④						
Input Capacitance	C _{iss}	V _{DS} =20V, V _{GS} =0V, f=1.0MHz		633		pF
Output Capacitance	C _{oss}			67		pF
Reverse Transfer Capacitance	C _{rss}			58		pF
Total Gate Charge	Q _g	V _{DS} =20V, I _D =8A, V _{GS} =10V		12		nC
Gate Source Charge	Q _{gs}			3.2		nC
Gate Drain Charge	Q _{gd}			3.1		nC
Switching Parameters ④						
Turn-On DelayTime	t _{d(on)}	V _{DD} = 20V, R _L =2.5Ω V _{GS} =10V,R _{REN} =3Ω		4		ns
Turn-On Rise Time	t _r			3		ns
Turn-Off DelayTime	t _{d(off)}			15		ns
Turn-Off Fall Time	t _f			2		ns
Drain-Source Diode Characteristics and Maximum Ratings						
Maximum Continuous Drain to Source Diode Forward Current		I _s			20	A
Maximum Pulsed Drain to Source Diode Forward Current		I _{SM}			32	A
Drain to Source Diode Forward Voltage ²	V _{SD}	V _{GS} =0V, I _S = 8A			1.2	V

Note :

1. Repetitive Rating : Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t < 5 sec.
3. Pulse Test : Pulse Width≤300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production testing.

P-Channel Electrical Characteristics(T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static Parameters ③						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D = -250μA	-40			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-32V, V _{GS} =0V			-1	μA
Gate-Body leakage Current	I _{GSS}	V _{GS} =±20 V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D = -250μA	-1.0	-1.6	-2.5	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =-8A		35	45	mΩ
		V _{GS} =4.5V, I _D =-4A		47	70	mΩ
Dynamic Parameters ④						
Input Capacitance	C _{iss}	V _{DS} =-15V, V _{GS} =0V, f=1MHz		1004		pF
Output Capacitance	C _{oss}			108		pF
Reverse Transfer Capacitance	C _{rss}			80		pF
Total Gate Charge	Q _g	V _{DS} =-20V, V _{GS} =-4.5V, I _D =-12A		9		nC
Gate Source Charge	Q _{gs}			2.54		nC
Gate Drain Charge	Q _{gd}			3.1		nC
Switching Parameters ④						
Turn-On DelayTime	t _{d(on)}	V _{DD} =-15V, V _{GS} =-10V, R _G =3.3Ω, I _D =-1A		19.2		ns
Turn-On Rise Time	t _r			12.8		ns
Turn-Off DelayTime	t _{d(off)}			48.6		ns
Turn-Off Fall Time	t _f			4.6		ns
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current ^{1,5}	I _S	V _G =V _D =0V, Force Current			-15	A
Pulsed Source Current ^{2,5}	I _{SM}				-40	A
Drain to Source Diode Forward Voltage ²	V _{SD}	V _{GS} =0V, I _S =-1A, T _J =25°C			-1	V

Note :

1. Repetitive Rating : Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t < 5 sec.
3. Pulse Test : Pulse Width≤300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production testing.

N-Channel Typical Characteristics

Figure 1: Output Characteristics

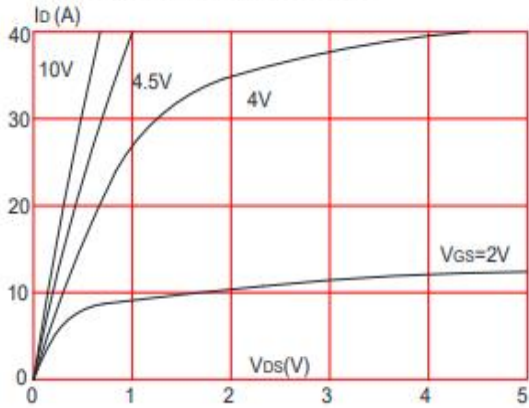


Figure 2: Typical Transfer Characteristics

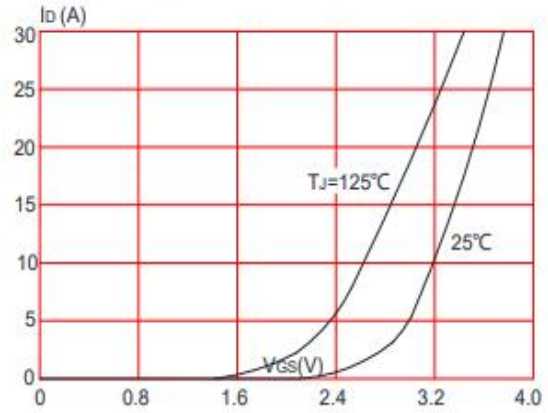


Figure 3: On-resistance vs. Drain Current

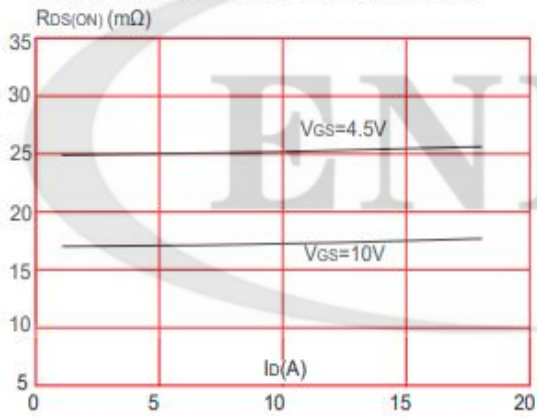


Figure 4: Body Diode Characteristics

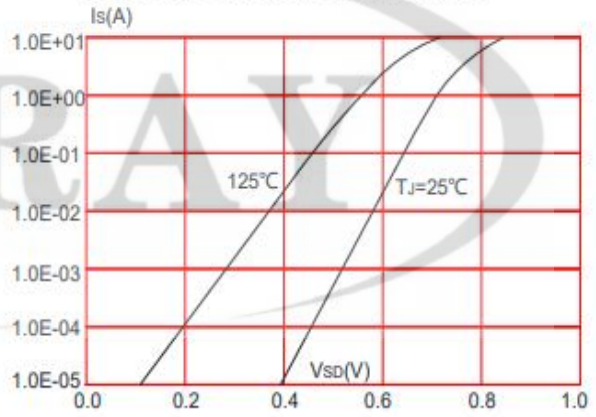


Figure 5: Gate Charge Characteristics

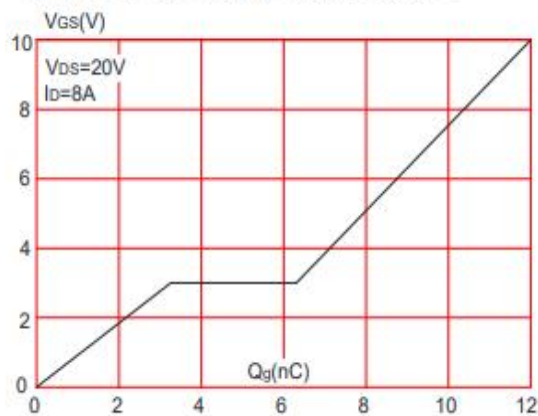
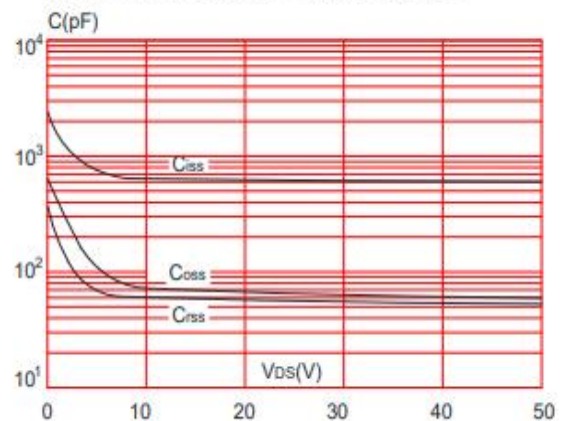


Figure 6: Capacitance Characteristics



N-Channel Typical Characteristics

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

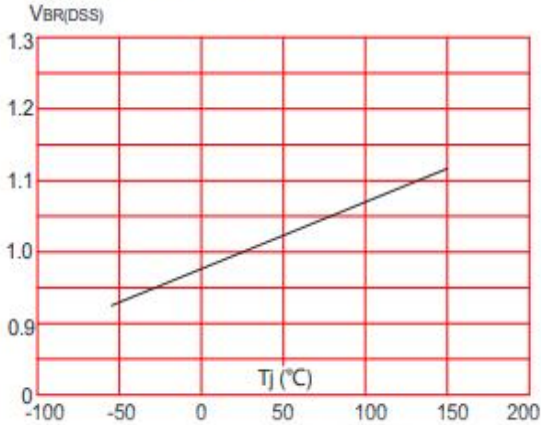


Figure 8: Normalized on Resistance vs. Junction Temperature

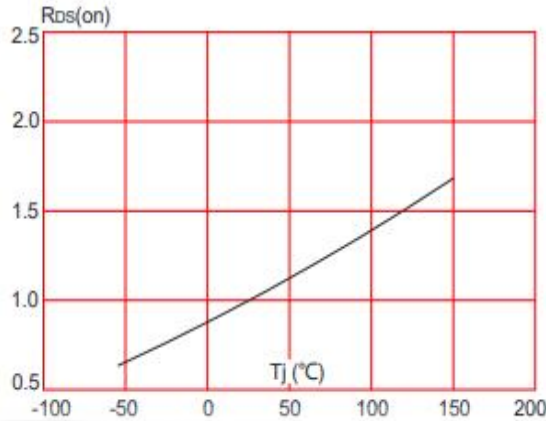


Figure 9: Maximum Safe Operating Area

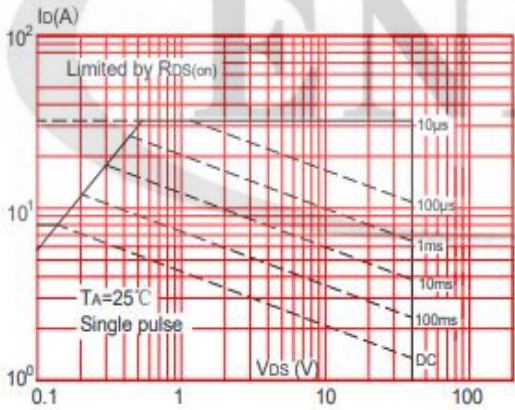


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

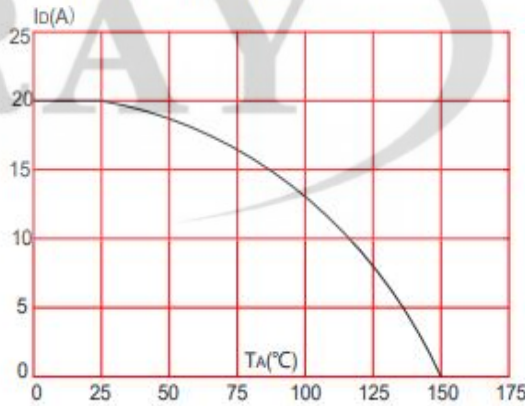
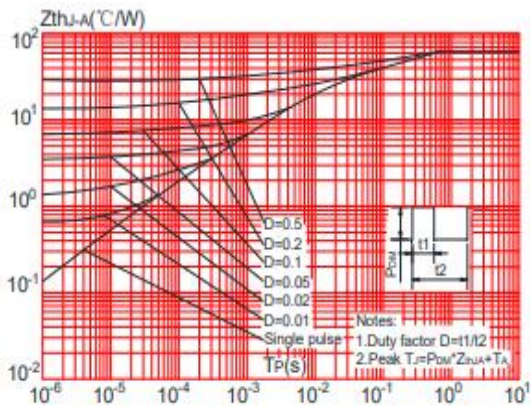


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



P-Channel Typical Characteristics

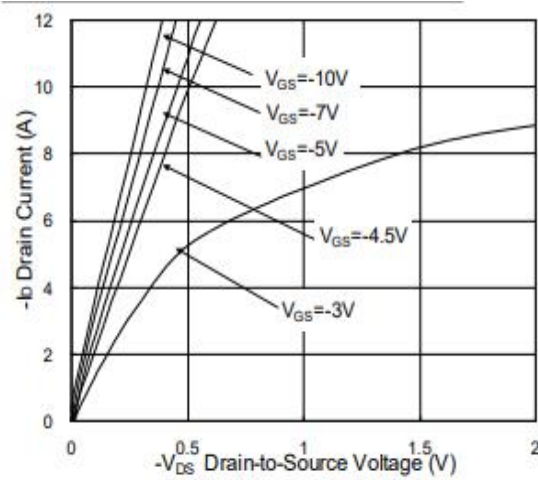


Fig.1 Typical Output Characteristics

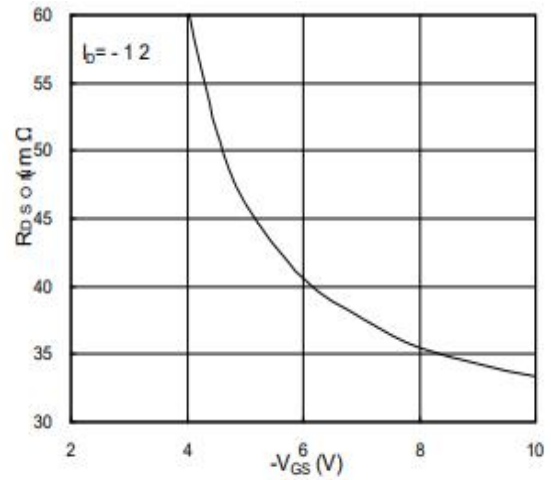


Fig.2 On-Resistance v.s Gate-Source

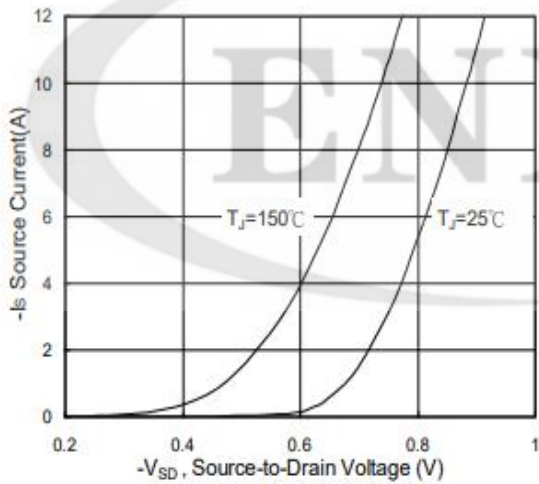


Fig.3 Forward Characteristics of Reverse

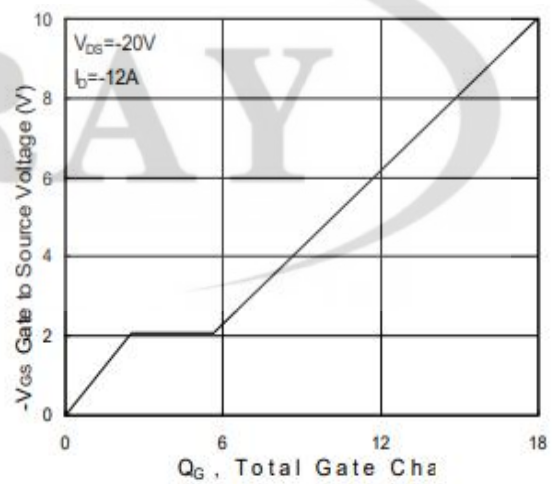


Fig.4 Gate-Charge Characteristics

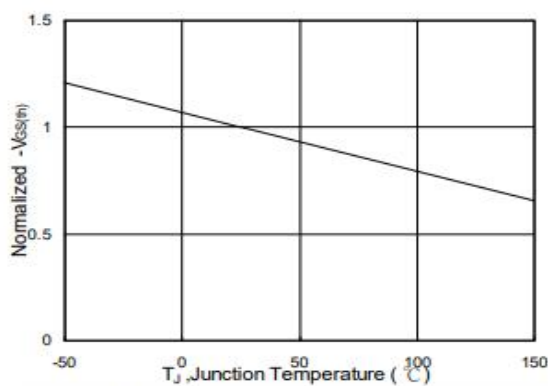


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

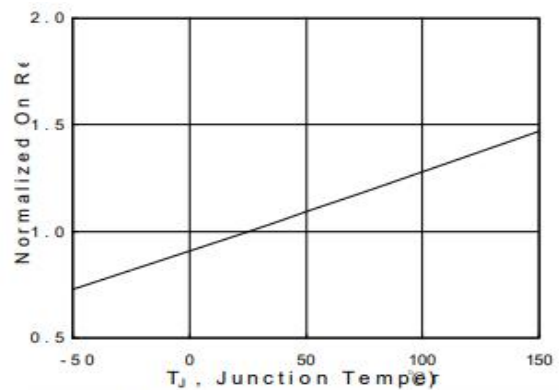


Fig.6 Normalized $R_{DS(on)}$ v.s T_J

P-Channel Typical Characteristics

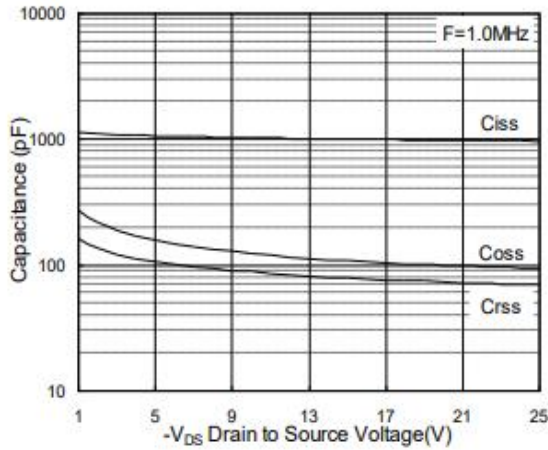


Fig.7 Capacitance

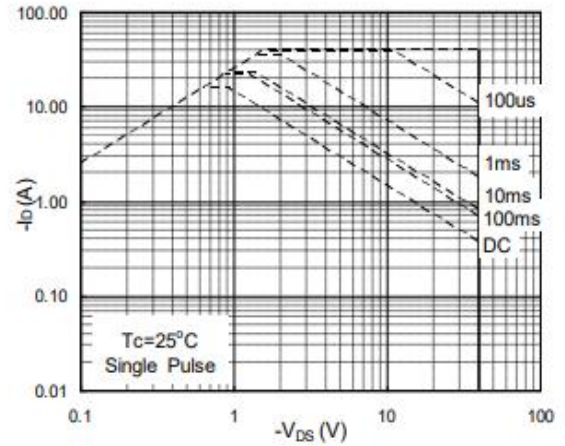


Fig.8 Safe Operating Area

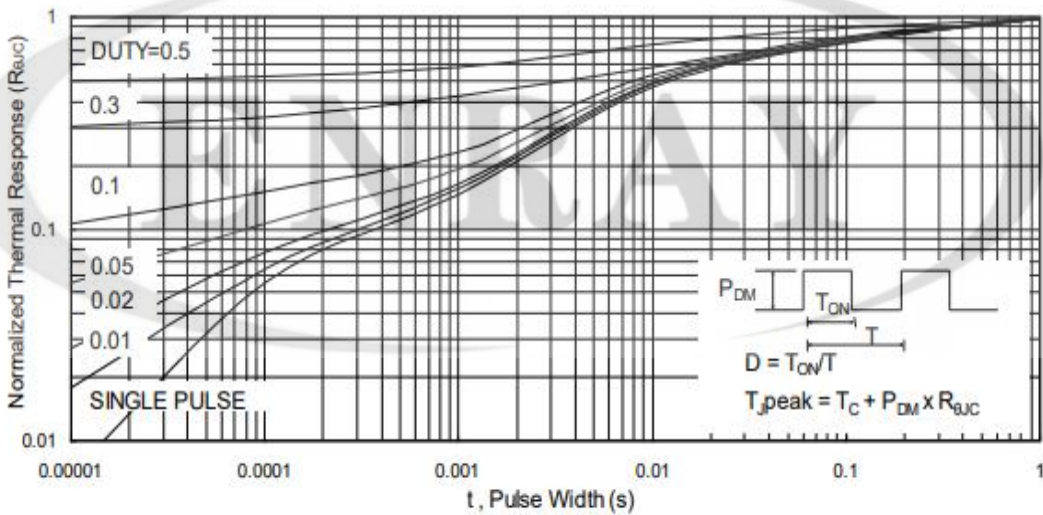


Fig.9 Normalized Maximum Transient Thermal Impedance

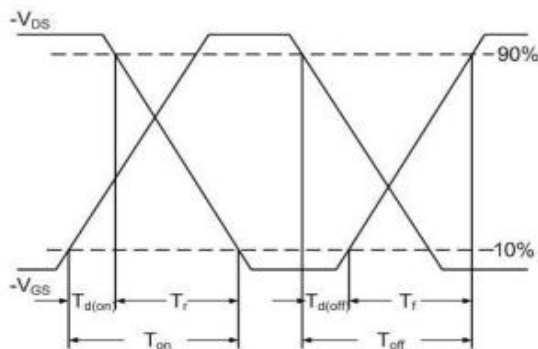


Fig.10 Switching Time Waveform

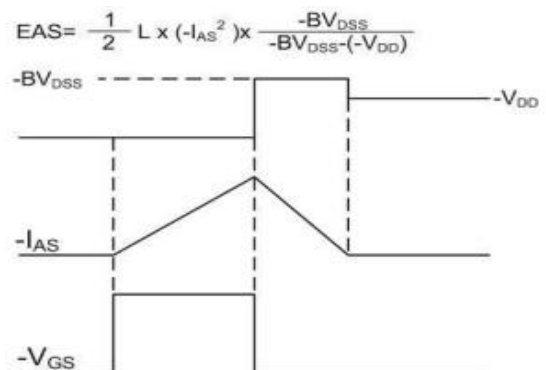


Fig.11 Unclamped Inductive Waveform

TO-252-4L Package Outline Dimensions

